ATTORNEY DOCKET NO. NC25779 U.S. SERIAL NO. 09/870,039 PATENT

coated with an electrically conductive material, an improvement of a connector for electrically connecting the electronic circuit component in affixed engagement with the substrate, said connector comprising:

at least a first pin member affixed to the electrical circuit component to form a portion thereof, said first pin member of an electrically-conductive material that exhibits physical-memory characteristics, said first pin member positioned at least alternately in a first configuration and a memory configuration, said first pin member extending into the first indent when the electronic circuit is seated upon the scating surface and said first pin member is molded in the first configuration, said first pin member reconfigured into the memory configuration responsive to heating to a deformation threshold temperature such that, when positioned in the memory configuration, first clutching forces exerted by said first pin member cause flexing engagement of said first pin member with the electrically conductive material coating the first indent.

- 3. (Twice Amended) In the electronic circuit component of claim 1, the at least the first indent comprises the first indent and at least a second indent and wherein said connector further comprises at least a second pin member, said first pin member extending into the first indent and said second pin member extending into the second indent when the electronic circuit component is seated at the seating surface.
- 4. (Twice Amended) In the electronic circuit component of claim 3, said second pin member is also positioned at least alternately in the first configuration and the memory configuration, said second pin member molded in the first configuration when the electronic circuit is scated upon the seating surface, said second pin member reconfigured into the memory configuration responsive to Page 2 of 2

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ATTORNEY DOCKET NO. NC25779 U.S. SERIAL NO. 09/870,039 PATENT

heating to a deformation threshold temperature such that, when positioned in the memory configuration second clutching forces exerted by said second pin member cause flexing engagement of said second pin member with electrically conductive material coating the second indent.

- 5. (Twice Amended) In the electronic circuit component of claim 4, said first pin member is affixed to extend beneath a first side edge of the electronic circuit component, wherein said second pin member is affixed to extend beneath a second said edge of the electronic circuit component, and wherein the first clutching force and the second clutching force are exerted in opposing directions.
- 7. (Twice Amended) In the electronic circuit component of claim 1, said first pin member comprises an elongated camber-leg which exhibits a cambered-configuration when configured in the memory configuration.
- 8. (Amended) In the electronic circuit component of claim 7, the clongated camber-leg forming said first pin member exhibits an amount of camber when configured in the memory configuration greater than when the elongated camber-leg forming said first pin member is configured in the first configuration.
- 9. (Twice Amended) In the electronic circuit component of claim 1, the at least the first indent formed in the substrate is defined by a first through hole formed to extend therethrough and wherein said first pin member extends through the first through hole when the electronic circuit component is seated at the scating surface.
- 10. (Twice Amended) In the electronic circuit of claim 9, said first pin member defines a proximal side portion affixed to the electronic circuit component and a distal side portion extending beyond the substrate when the electronic circuit component is seated upon the Page 3 of 3

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ATTORNEY DOCKET NO. NC25779 U.S. SERIAL NO. 09/870,039 PATENT

substrate.

- 11. (Twice Amended) In the electronic circuit component of claim 10, said first pin member further comprises a foot piece positionable to abut against a bottom face surface of the substrate when said first pin member is configured in the memory configuration and the electronic circuit component is sealed upon the scating surface, thereby to prevent removal of the electronic circuit component out of the seating surface.
- 12. (Twice Amended) In the electronic circuit component of claim 11, when the electronic component is scated upon the scating surface, said first pin member extends through the first through hole when said first pin member is configured in the first configuration, said first pin member of diametrical dimensions preventing translation of said first pin member out of the first through hole subsequent to positioning of the electronic circuit component upon the scating surface and configuring said first pin member into the memory configuration.

## REMARKS

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By telephonic communication of 3 March 2003, the Examiner notified the undersigned of the potential allowability of the pending claims of the patent application. The Examiner, however, noted some problems with various terminology recited in the claims. Additionally, the Examiner noted that the non-elected claims, claims 15-20, of the invention of Group I should be cancelled. And, the Examiner also noted objection to improper hatch markings to Figure 2 of the drawings.

Page 4 of 4